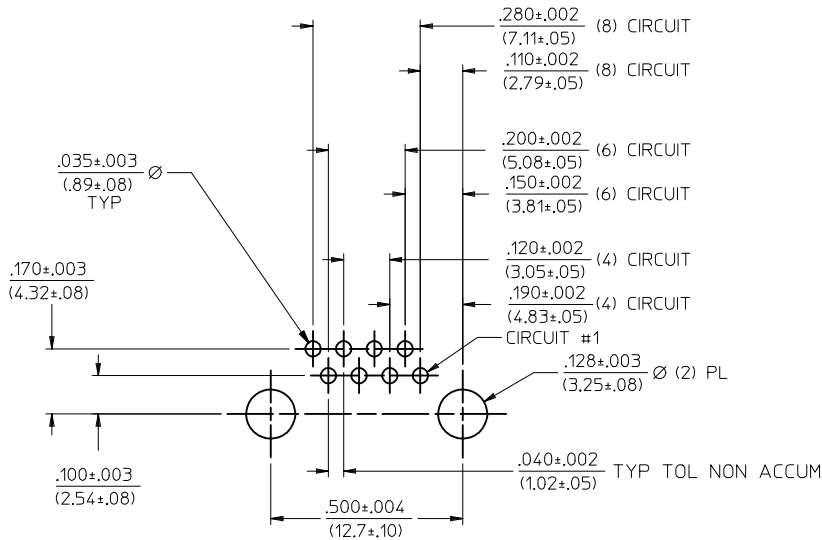
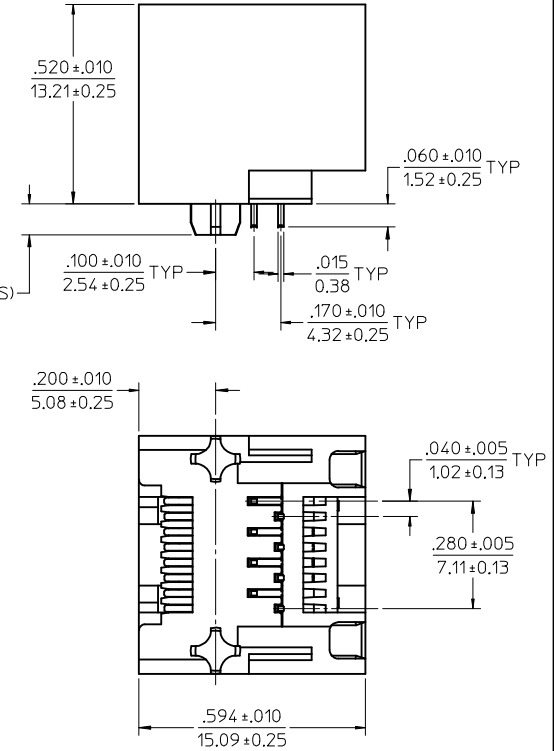
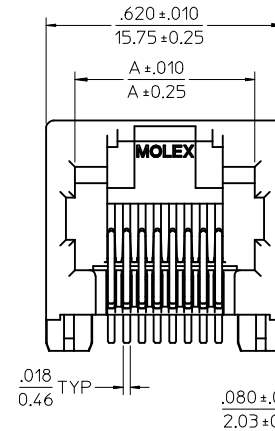


NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN EXTRUDED TUBES
PER PACKAGING SPECIFICATION PK-43860-004
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR
REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS .039/1.00

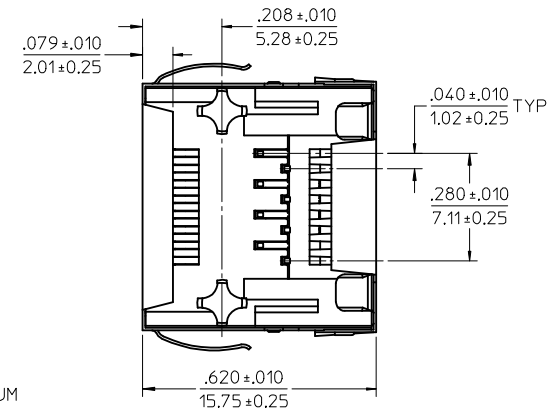
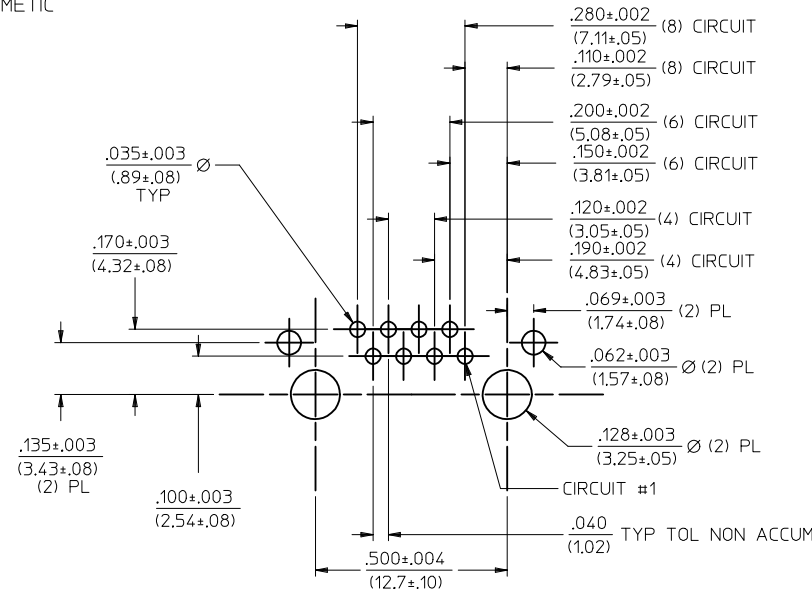
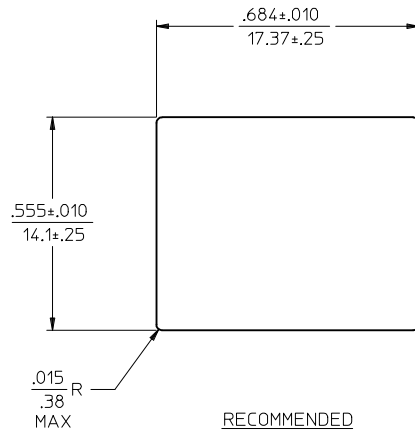
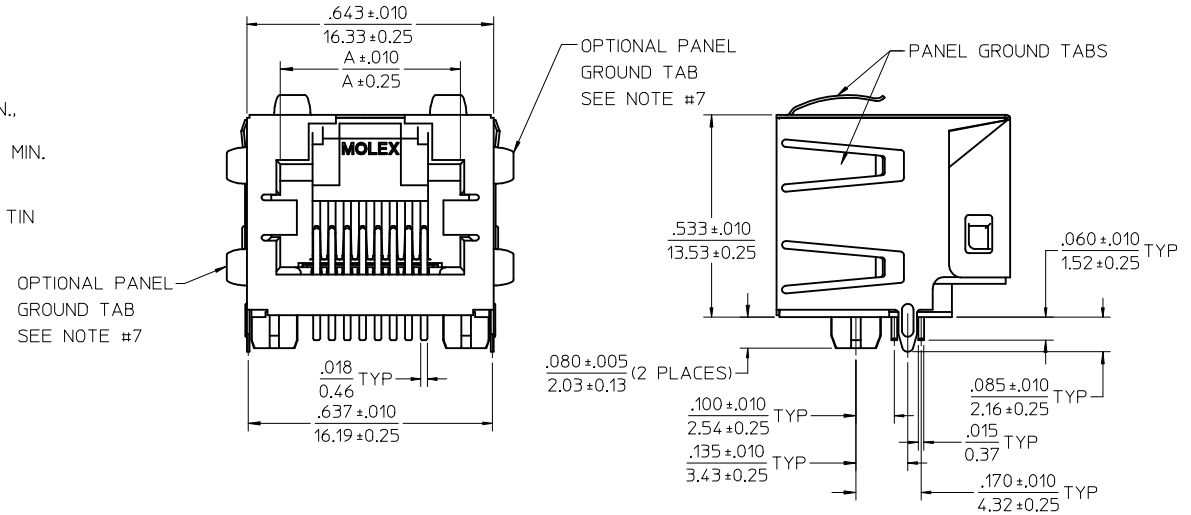
MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS
44380-0001	8	.470/11.94	8
44380-0002	6	.389/9.88	6
44380-0003	6	.389/9.88	4
44380-0019	8	.470/11.94	4

UPDATE VIEWS EC NO: UCP2015-0148 2014/07/16 DRW:NGUYEN 2014/07/16 CHKD:JBELL 2015/05/19 APPR:FSMITH REV	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
					IN/MM		4:1	INCH	
					DRAWN BY	DATE	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)		
					MAYO	1999/04/09			
					CHECKED BY	DATE			
					ROBERTS	1999/04/09			
					APPROVED BY	DATE	molex		
					ROBERTS	1999/04/09			
					MATERIAL NO.		DOCUMENT NO.		
		SEE CHART		SD-44380-001		1 OF 5			

SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

NOTES

- 1) MATERIAL:
HOUSING: GLASS FILLED NYLON, 94V-0 COLOR: BLACK
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
SHIELD: BRASS
- 2) PLATING:
TERMINALS:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
SHIELD:
100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES
(1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN
- 3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003
- 4) PACKAGING OPTIONS:
CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS
PER PACKAGING SPECIFICATION PK-44380-005
OPTION (44380-2004) PACKAGED IN TAPE AND REEL
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY
- 6) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS
- 7) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
- 8) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



PC BOARD LAYOUT
COMPONENT SIDE OF BOARD
RECOMMENDED PC BOARD THICKNESS: .039/1.00

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0004	8	.470/11.94	8	ALL
44380-0005	6	.389/9.88	6	ALL
44380-0006	6	.389/9.88	4	ALL
44380-0013	8	.470/11.94	8	SEE NOTE #7
44380-0014	6	.389/9.88	6	SEE NOTE #7
44380-0015	6	.389/9.88	4	SEE NOTE #7
44380-2004	8	.470/11.94	8	ALL

SEE SHEET 1 EC NO: UCP2015-0148 DRAWN: NGUYEN 2014/07/16 CHKD: JELL 2014/07/16 APPR: FSL/TH 2015/05/19	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± --- ± --- 1 PLACE ± --- ± --- 0 PLACE ± ± ANGULAR ±1/2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE IN/MM DRAWN BY DATE MAYO 1999/04/09 CHECKED BY DATE ROBERTS 1999/04/09 APPROVED BY DATE ROBERTS 1999/04/09	SCALE 4:1 DESIGN UNITS INCH THIRD ANGLE PROJECTION	INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex SD-44380-001	SHEET NO. 2 OF 5

NOTES

1) MATERIAL:
HOUSING:
GLASS FILLED NYLON, 94V-0, COLOR: BLACK
TERMINALS:
PHOSPHOR BRONZE, .015/(0.38) THK
LIGHTPIPE:
POLYCARBONATE- WAVE OR HAND SOLDER ONLY
(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW
SOLDER PROCESSES)
POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)

2) PLATING:
TERMINAL:
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.

3) PRODUCT SPECIFICATION:
CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX
PRODUCT SPECIFICATION PS-43860-003

4) PACKAGING:
PER PACKAGING SPECIFICATION PK-43860-004

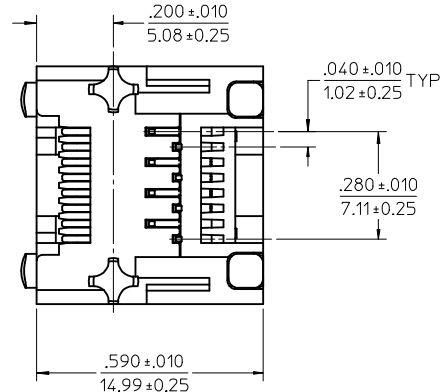
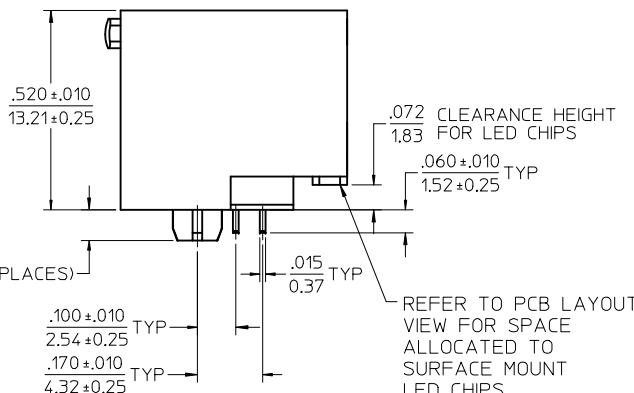
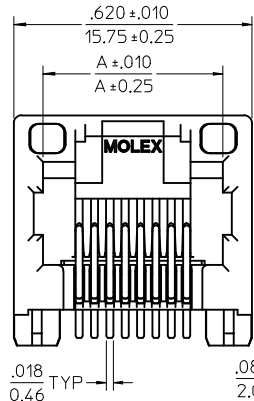
5) APPLICATION SPECIFICATION: AS-43860-001.

6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.

8) REFER TO PAGE (5) OF (5) FOR RECOMMENDED PCB LAYOUT.

9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC
SPECIFICATION PS-45499-002.



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONNECTOR SIZE	DIM. "A"	CIRCUITS	SEE SHEET 1 EC NO: UCP2015-0148 2014/07/16 DRAWN: NGUYEN CHKD: J.BELL 2014/07/16 APPR: F.SMITH 2015/05/19	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
									IN/MM		4:1	INCH			
44380-0007	POLYCARBONATE	8	.470/11.94	8			▽=0	4 PLACES ± --- ± ---	mm INCH	DRAWN BY MAYO	DATE 1999/04/09	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT) molex MATERIAL NO. SEE CHART DOCUMENT NO. SD-44380-001 SHEET NO. 3 OF 5			
44380-0008	POLYCARBONATE	6	.389/9.88	6			▽=0	3 PLACES ± --- ± ---	mm INCH	CHECKED BY	DATE				
44380-0009	POLYCARBONATE	6	.389/9.88	4			▽=0	2 PLACES ± --- ± ---	mm INCH	ROBERTS	1999/04/09				
44380-0020	POLYSULFONE	8	.470/11.94	8				1 PLACE ± --- ± ---	mm INCH	APPROVED BY	DATE				
44380-0021	POLYSULFONE	6	.389/9.88	6				0 PLACE ± ±	mm INCH	ROBERTS	1999/04/09				
44380-0022	POLYSULFONE	6	.389/9.88	4					ANGULAR ±1/2°						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS															
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															

NOTES

1) MATERIAL:

HOUSING:

GLASS FILLED NYLON, 94V-0, COLOR: BLACK

TERMINALS:

PHOSPHOR BRONZE, .015/(0,38) THK

SHIELD:

BRASS

LIGHTPIPE:

POLYCARBONATE - WAVE OR HAND SOLDER ONLY

(NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)

POLYSULFONE - MAXIMUM REFLOW TEMPERATURE: 400°F (205°C)

2) PLATING:

TERMINAL:

SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,

SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,

WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.

SHIELD:

100 MICROINCHES (2.54 MICROMETERS) NICKEL OVER 50 MICROINCHES

(1.27 MICROMETERS) COPPER UNDERPLATE; PCB GROUND TABS DIPPED IN TIN.

3) PRODUCT SPECIFICATION:

CONNECTOR PERFORMANCE SPECIFICATIONS PER MOLEX

PRODUCT SPECIFICATION PS-43860-003.

4) PACKAGING:

CONNECTOR ASSEMBLIES IN THERMOFORMED TRAYS

PER PACKAGING SPECIFICATION PK-44380-005 .

5) APPLICATION SPECIFICATION: AS-43860-001.

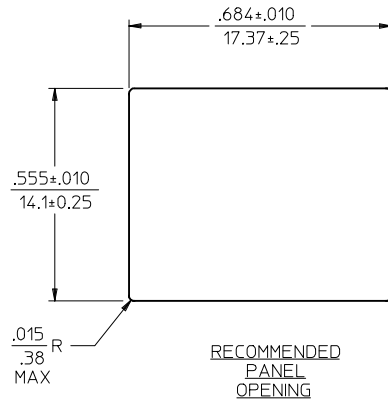
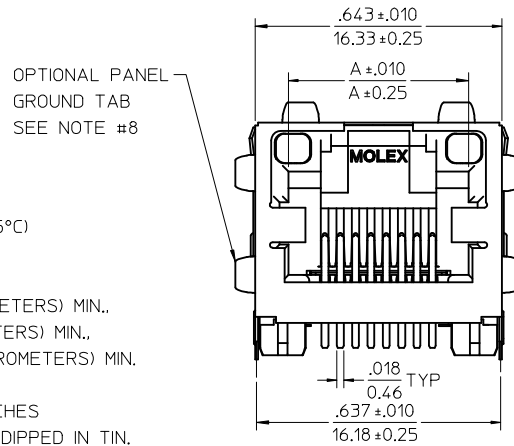
6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.

7) CONFORMS TO F.C.C. REGULATION PART 68.5 FOR MODULAR JACKS.

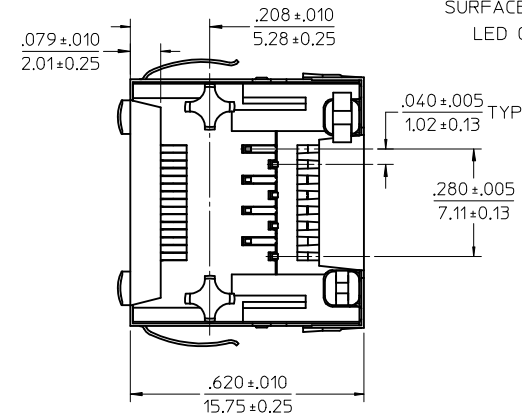
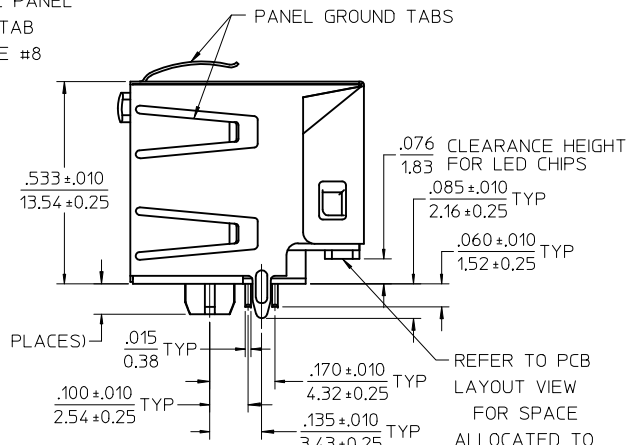
8) AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.

9) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.

10) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.



OPTIONAL PANEL GROUND TAB SEE NOTE #8



MATERIAL NUMBER	LIGHTPIPE MATERIAL	CONN SIZE	DIM. "A"	CIRCUITS	PANEL GROUND TABS
44380-0010	POLYCARBONATE	8	.470/11.94	8	ALL
44380-0011	POLYCARBONATE	6	.389/9.88	6	ALL
44380-0012	POLYCARBONATE	6	.389/9.88	4	ALL
44380-0016	POLYCARBONATE	8	.470/11.94	8	SEE NOTE #8
44380-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
44380-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
44380-1010	POLYSULFONE	8	.470/11.94	8	ALL
44380-1011	POLYSULFONE	6	.389/9.88	6	ALL
44380-1012	POLYSULFONE	6	.389/9.88	4	ALL
44380-1016	POLYSULFONE	8	.470/11.94	8	SEE NOTE #8
44380-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
44380-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

SEE SHEET 1

EC NO: WCP2015-0148

2014/07/16

DRW:NGUYEN

2014/07/16

CHKD:JBELL

2015/05/19

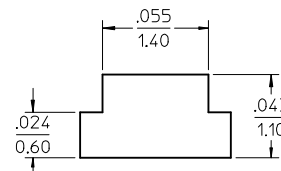
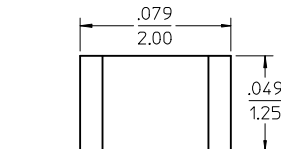
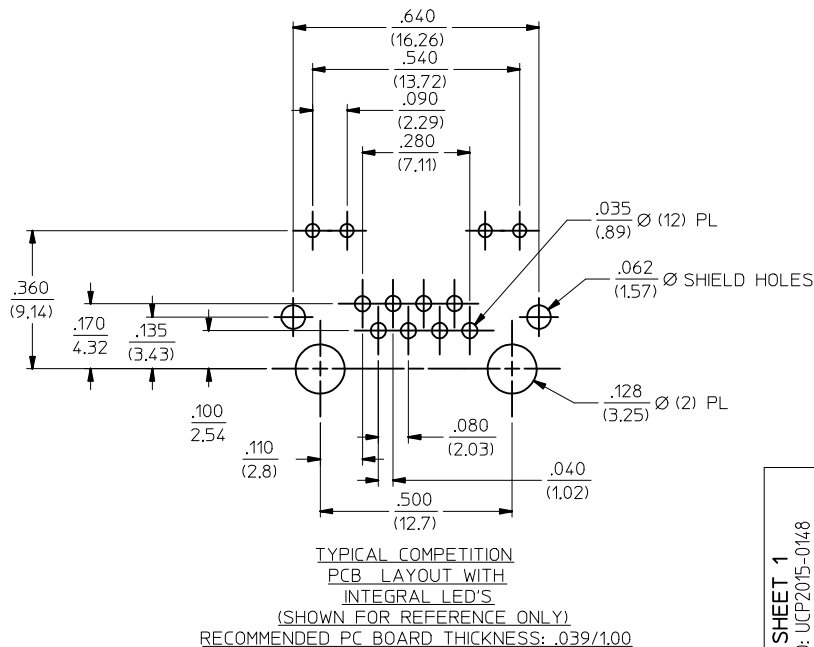
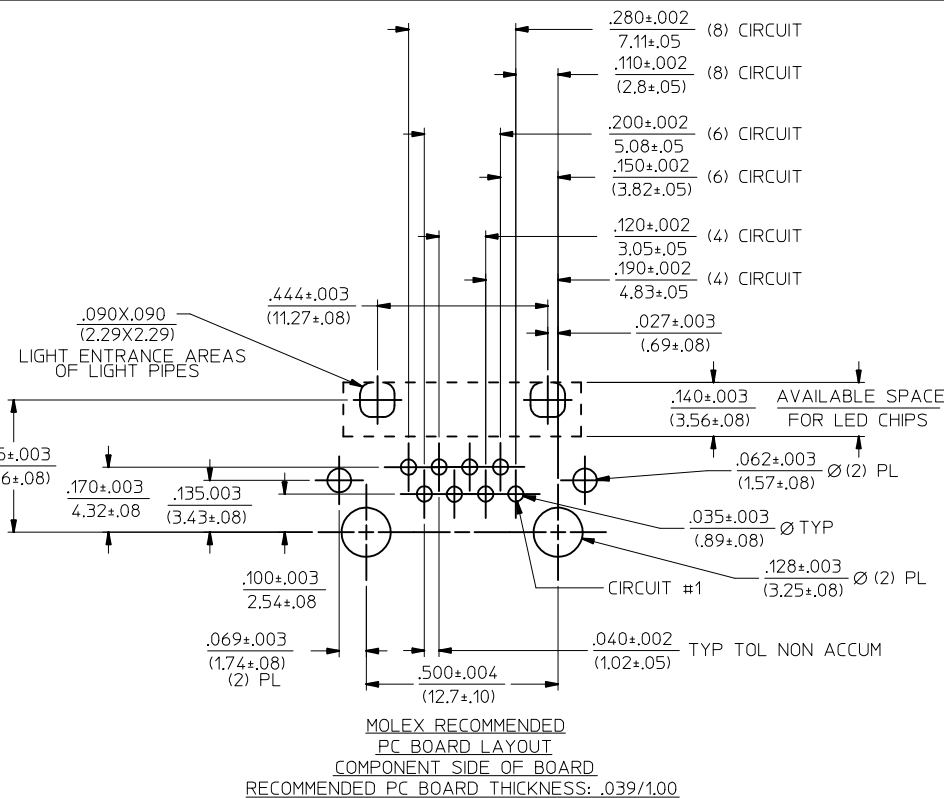
APPR:FSMITH

QUALITY SYMBOLS
▽=0
▽=0
▽=0

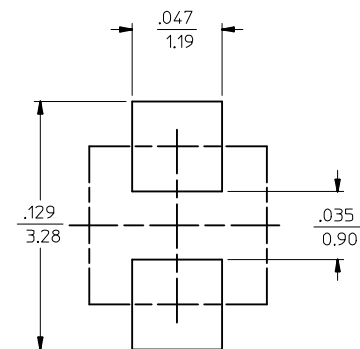
GENERAL TOLERANCES (UNLESS SPECIFIED)		
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± ---	± ---
1 PLACE	± ---	± ---
0 PLACE	±	±
ANGULAR ±1/2°		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

DIMENSION STYLE	
IN/MM	
DRAWN BY	DATE
MAYO	1999/04/09
CHECKED BY	DATE
ROBERTS	1999/04/09
APPROVED BY	DATE
ROBERTS	1999/04/09
MATERIAL NO.	
SEE CHART	
SIZE	THIS DRAWING CONT INCORPORATED AND
C	

J
I
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G
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E
D
C
B
A



RECOMMENDED SMT
LED DIMENSIONS
SCALE 20:1
(SEE NOTE 1)



RECOMMENDED SMT
LED SOLDER PATTERN
SCALE 20:1
(SEE NOTE 1)

NOTES:

1. FOR CROSS REFERENCE OF RECOMMENDED LEDS SEE MOLEX WEB SITE.

SEE SHEET 1 EC NO: UCP2015-0148 2014/07/16 DRAWN: NGUYEN 2014/07/16 CHKD: J.BELL 2015/05/19 APPR: F.S.MITH	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE IN/MM		SCALE 4:1	DESIGN UNITS INCH	 THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY MAYO	DATE 1999/04/09	TITLE INVERTED MODULAR JACK ASSEMBLY (MINI-PCI COMPLIANT)			
			4 PLACES ±---	±---	CHECKED BY ROBERTS	DATE 1999/04/09				
			3 PLACES ±---	±---	APPROVED BY ROBERTS	DATE 1999/04/09				
			2 PLACES ±---	±---	SEE CHART					
			1 PLACE ±---	±---						
			0 PLACE ±	±	MATERIAL NO.		DOCUMENT NO.			SHEET NO.
			ANGULAR ±1/2°		SD-44380-001		5 OF 5			
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE C		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

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moschip.ru_6

moschip.ru_9